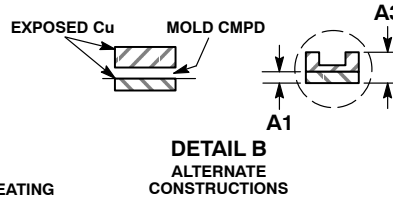
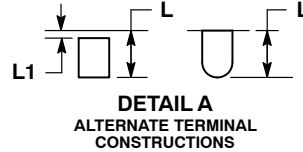
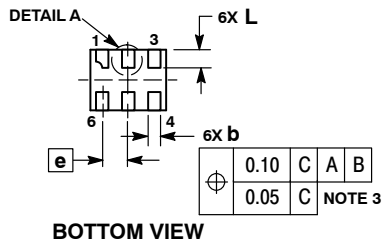
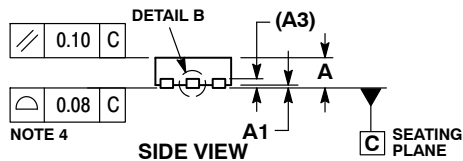
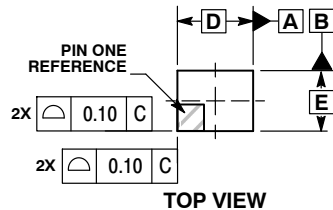
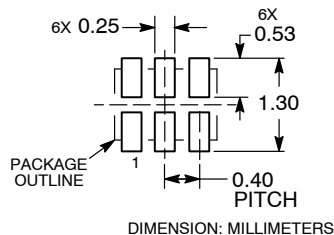

SCALE 4:1
UDFN6, 1.25x1, 0.4P
CASE 517BM
ISSUE O
DATE 20 JUL 2010

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.15	REF
b	0.15	0.25
D	1.25	BSC
E	1.00	BSC
e	0.40	BSC
L	0.20	0.40
L1	---	0.15

RECOMMENDED SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN6, 1.25x1, 0.4P	PAGE 1 OF 1

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